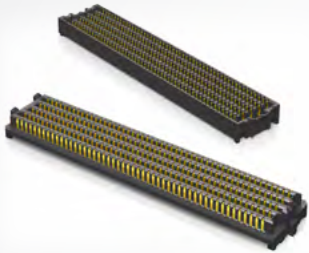


DUAL SOURCED PRODUCTS



SEARAY™

Dual Sourced by Molex®
SEARAY™ (SEAM/SEAF Series) is a high-density, high-speed open-pin-field array with maximum routing flexibility up to 500 I/Os. Also features Samtec's rugged Edge Rate® contact system for lower insertion and extraction forces.



Edge Rate®

Dual Sourced by Hirose
Samtec's 0.80 mm (.0315") Edge Rate® interface system (ERM8/ERF8 Series) is ideal for high-speed, high-cycle applications. The rugged Edge Rate® contact features 1.50 mm contact wipe and is optimized for superior signal integrity performance. It is available up to 200 I/Os with stack heights from 7 mm to 16 mm.



Q Rate®

Dual Sourced by Hirose
Q Rate® (QRM8/QRF8 Series) is Samtec's next generation of high-speed, controlled impedance interconnects. The rugged Edge Rate® contact system combined with an integral ground/power plane provides superior electrical performance while a slim body design minimizes PCB real estate. Q Rate® is available with up to 156 I/Os in 7 mm and 14 mm stack heights.



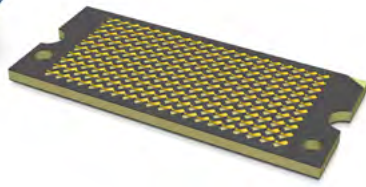
Q Strip®

Dual Sourced by TE Connectivity as the MICTOR SB
Q Series® is Samtec's most popular high-speed mezzanine connector family. As part of this family, Q Strip® features an integral ground plane with stack heights as low as 5 mm and is available in 3 centerlines.



FireFly™ Micro Flyover System™

Dual Sourced by Hirose
Samtec's patented FireFly™ Micro Flyover System™ (ECUE/ECUO, UCC8, UEC5 Series) is the first future-proof interconnect system that gives designers a choice of using either optical or copper interconnects with the same micro footprint to meet today's data rate requirements and the next generation. Data connections to 28+ Gbps bypass the board and other components therefore simplifying board layout design and enhancing signal integrity.



Z-Ray® Ultra-Low Profile Micro Array Interposer

Samtec's Z-Ray® (ZA8/ZA1 Series) one-piece array features a 1.00 mm ultra-low profile body height and is available in both 0.80 mm and 1.00 mm pitch. Choice of dual compression contacts or single compression contacts with solder balls. Highly customizable pin count, shapes and patterns, X-Y-Z axes flexibility, increased cycle life, low normal force and 28+ Gbps performance.



SkyRay™

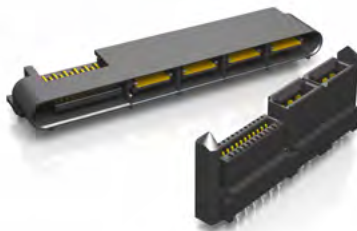
Dual Sourced by Hirose
The Differential Array Interconnect (TPAR/TPAF Series) is a 1.50 mm x 1.75 mm pitch, three-piece elevated system. This system is optimized for differential pair signaling with up to 300 signals and 28+ Gbps performance. Stack heights from 18-40 mm are available. Engineered for 40 Gbps and beyond with crosstalk canceling technology, dampening material, prop delay mitigation and impedance matching.



ExaMAX® High-Speed Backplane System

Dual Sourced by AFCI
ExaMAX® high-speed backplane interconnects deliver 28 Gbps electrical performance while offering a migration path to 56 Gbps. The contact system achieves two reliable points of contact, minimizes residual stub, provides low mating force and excellent normal force. Signal wafers feature 40 or 72 staggered differential signal pairs and incorporate a one-piece, embossed ground structure to significantly reduce crosstalk.

DUAL SOURCED PRODUCTS



EXTreme Ten60Power™

Dual Sourced by Molex®

This modular high-current power and signal connector system (ET60S/ET60T Series) is ideal for coplanar and perpendicular applications. The EXTreme Ten60Power™ connector provides maximum current-to-length ratio packaged in a 10 mm low profile body that enhances airflow within the power system.

EXTreme LPHPower™

Dual Sourced by Molex®

EXTreme LPHPower™ (LPHS/LPHT Series) is a high-current power and signal connector system with double stacked power blades for high density. The extremely low 7.50 mm profile height allows greater system airflow and takes up 53% less space than connectors with the same current rating. Traditional two-piece connector system or socket mates with standard 1.60 mm and 2.36 mm thick cards.

HD Mezz

Dual Sourced by Molex®

HD Mezz (HDAM/HDAF Series) is a 1.20 mm x 2.00 mm grid interconnect system for elevated, high-speed board-to-board applications. The high-density array open-pin-field design allows either single-ended or differential pair routing.

AFI

Dual Sourced by Amphenol®

This 50 Ω interface (AFI Series) is an ideal solution for board-to-board RF applications, especially military and broadband marketplaces. The AFI interface configuration allows for industry leading "float" to compensate for axial and radial misalignment due to packaging tolerances.



AccliMate™ Miniature Sealed Cable Assembly

Dual Sourced by Hirose

Samtec's AccliMate™ Mini Push-Pull System (MCP/MCR Series) meets IP67 requirements for dust and water when submerged 1 m deep for 30 minutes. It features a push-pull latching system and is designed for cable-to-panel or cable-to-cable applications. Standard 28 AWG wire, polarizing keys and visual alignment indicators, which protect from misalignment. Built-in cable strain relief, and optional dust caps are also available.

HD-BNC™

Dual Sourced by Amphenol®

Samtec's high-density BNC small form factor RF connector with quarter turn coupling (HDBNC Series) is an ideal solution for interfaces strained due to heavy, ganged cabling. It is lightweight, yet more reliable than traditional push-pull latching systems and offers four times the panel density of traditional BNCs.